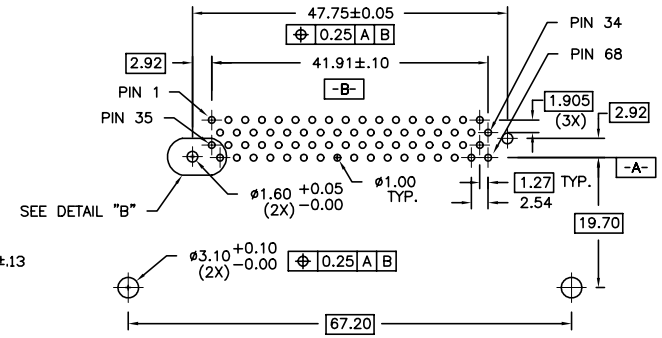
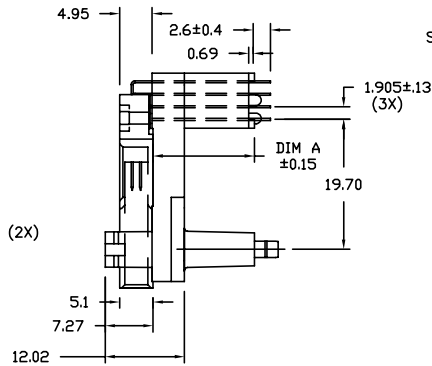
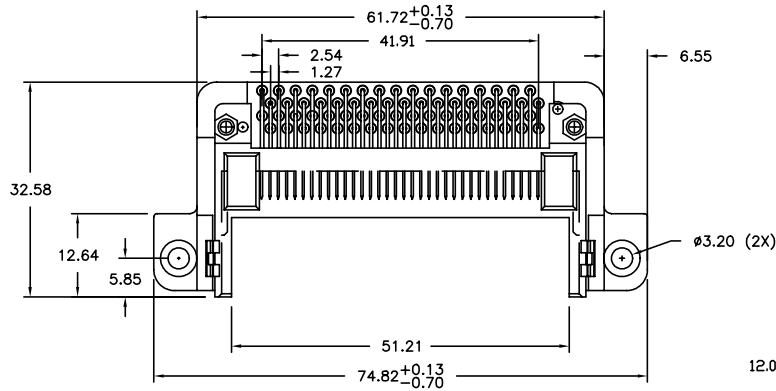
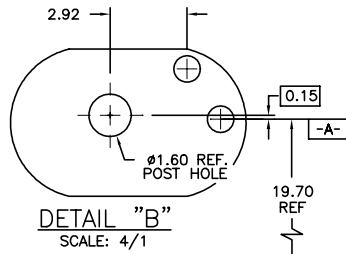
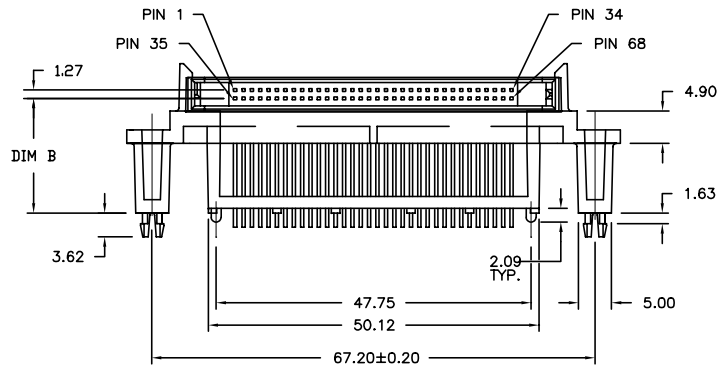


PRODUCT NO.	DIM "A"	DIM "B"
10120633-001LF	8.90	10.8



P.C.B. LAYOUT



NOTES:

- MATERIAL:  
CONTACT - COPPER ALLOY  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94-V0 BLACK
- PLATING:  
CONTACT - ALL OVER 0.5um NICKEL UNDER PLATING  
0.1um GOLD OVER 0.5um PALLADIUM  
NICKEL SELECTIVE PLATING ON CONTACT.  
2.5um PURE TIN PLATING ON LEAD FREE SOLDER TAIL
- MATING CONNECTOR  
JEIDA/PCMCIA SPECIFICATION
- IF LEAD FREE P/N. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- IF LEAD FREE P/N. PACKAGING MEETS GS-14-920 SPECIFICATION
- LEAD FREE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- PRODUCT SPECIFICATION APR-12-031,  
PACKING SPECIFICATION BUS-14-357

mat'l. code		surface ASME Y14.5 / tolerance ASME Y14.5		projection	product family PCMCIA	
ltr	ecnr	nodr	date	tolerances unless otherwise specified		title
A	-	ZK	04/13/12	angle 0°±2'	MM	HEADER ASSEMBLY W/STANDOFF
B	BLX-N-012546	ZK	06/15/12		0.XX±0.3 0.XX±0.13 0.XXX±0.05	
dr	ZK HU	04/13/12			dwg no	sheet 1 of 1 size
enr	ZK HU	04/13/12			10120633	A4
chr	RICK BIAN	04/13/12				
appd	RICK BIAN	04/13/12				
sheet	revision	B				
index	sheet	1				

